

SPECIFICATION

Part No.	:	DSGP.1575.18.2.A.02
Description	:	GPS L1 / GALILEO E1 1575MHz 18*18*2mm Ceramic Patch SMT Antenna
Features	:	2.4 dBi Peak Gain for GPS/GALILEO Band Dimensions: 18 x 18 x 2mm SMT Direct Mount Ceramic Patch Antenna
		TS16949 Approved RoHS Compliant





1. Introduction

The DSGP.1575.18.2.A.02 is a ceramic GPS L1 / GALILEO E1 passive patch antenna, 18mm square, with a low profile of 2mm thickness. It is designed for applications in space constrained navigation devices, vehicle tracking/fleet management systems, as well as telematics devices.

The antenna has been tuned on a 50 x 50 mm ground plane, working at 1575.42MHz with a 2.4 dBi gain. The ceramic patch is mounted via SMT process, ideal for high volume low cost assembly. It is manufactured and tested in a TS16949 first tier automotive approved facility.

For further optimization to customer specific device environments where ground-plane size is different, custom tuned patch antennas can be supplied. For more details please contact your regional Taoglas sales office.



2. Specification

ELECTRICAL					
Application Bands	GPS/GALILEO				
Operation Frequency (MHz)	1575.42 ±1.023				
Return Loss (dB)	< -10				
Gain at Zenith (dBi)	2.4				
Efficiency (%)	55.94				
Impedance	50 ohms				
MECHANICAL					
Ceramic Dimension (mm)	18 x 18 x 2				
Weight (g)	2.9				
ENVIRONMENTAL					
Operation Temperature	-40°C to 85°C				
Humidity	Non-condensing 65°C 95% RH				

* Antenna properties were measured with the antenna mounted on 50*50mm Ground Plane Taoglas Part # DSGPD.18B



3. Antenna Characteristics

3.1. Return Loss











3.3. Average Gain

3.4. Peak Gain





4. Antenna Radiation Pattern

4.1. Measurement Setup

The DSGP.1575.18.2 antenna is tested with 50mm*50mm ground plane in a

CTIA certified ETS-Lindgren Anechoic Chamber. The test setup is shown below.





4.2. 2D Radiation Pattern



XY Plane











4.3. 3D Radiation Pattern





5. Mechanical Drawing (Unit: mm)





6. Evaluation Board (DSGPD.18B) (Unit: mm)



	Name	Material	Finish	QTY
1	PCB SMA(F) ST	Brass	Gold	1
2	DSGP.1575.18.2.A.02 Antenna	Ceramic	Clear	1
3	PCB (50x50x1mm)	Composite	Black	1

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7. PCB Footprint Recommendation









8. Recommended Reflow Soldering Profile

DSGP.1575.18 can be assembled following Pb-free assembly. According to the Standard IPC/JEDEC J-STD-020C, the temperature profile suggested is as follow:

Phase	Profile Features	Pb-Free Assembly (SnAgCu)
PREHEAT	Temperature Min(Tsmin)	150°C
	Temperature Max(Tsmax)	200°C
	Time(ts) from (Tsmin to Tsmax)	60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	Temperature(TL)	217°C
	Total Time above TL (tL)	30-100 seconds
PEAK	Temperature(TP)	260°C
	Time(tp)	2-5 seconds
RAMP-DOWN	Rate	3°C/second(max)
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
	Solder Paste Model	SHENMAO PF606-P26

The graphic shows temperature profile for component assembly process in reflow ovens



Soldering Iron condition : Soldering iron temperature 270°C±10°C.

Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron



9. Packaging







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